

Description

AW 2925U is a two-part acrylic adhesive designed for thermally conductive structural bonding.

Features

- Recommended substrates: plastic, metal, ceramic
- Thermal conductivity
- Excellent bonding strength (including lap shear, T-peel and impact strength)
- Excellent heat resistance
- Fast cure (5-10 mins @ 10-28°C)

Uncured Properties

Chemical Type	Modified Acrylate
Appearance	
Part A	Blue
Part B	Pale Yellow
Viscosity @ 25°C [mPa.s]	
Brookfield LVDV, spindle 7# @ 5rpm	
Part A	800,000
Part B	1,000,000
Mix Ratio A:B	
By Volume	4:1
Specific Gravity [g/cm³]	~1.6
Shelf Life @ 10-28°C [months]	6

Curing Conditions

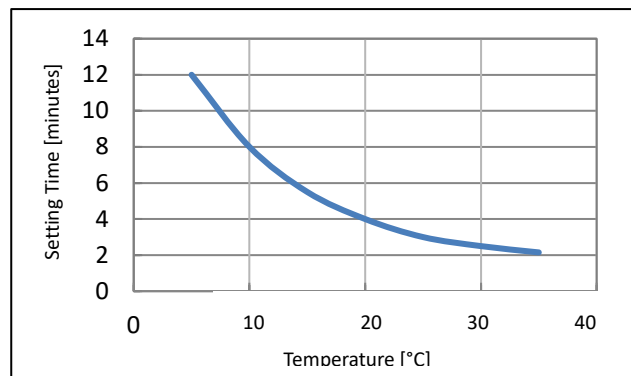
Setting Time @ 10-28°C [mins]	3-5
Fixture Time @ 10-28°C [mins]	6-10
Full Curing @ 10-28°C [hrs]	24

Cured Properties

Hardness [Shore D]	72
ASTM D2240	
Lap Shear Strength [MPa]	15
ASTM D1002	
Elongation at Break [%]	5
ASTM D638	
Tensile Strength [MPa]	20
ASTM D638	
Thermal Conductivity [W/m·K]	1.0
ASTM D2214	
Glass Transition Temperature (Tg) [°C]	80
ASTM D3418	
Coefficient of Thermal Expansion [ppm/°C]	
CTE1	45
CTE2	100
ASTM D3386	
Young's Modulus [MPa]	1,600
Surface Resistivity [ohm-cm]	>1.0x10 ¹⁴
ASTM D257	
Volume Resistivity [ohm-cm]	>1.0x10 ¹³
ASTM D257	

Setting time vs. various temperatures

Substrate: Aluminum



Directions for Use

1. Remove surface contaminants such as paint, oxide films, oils, dust, mold release agents and any other surface contaminants before bonding.
2. Use gloves to minimize skin contact.
3. Dual cartridges: to start a new cartridge, remove cartridge cap and dispense a small amount of adhesive and make sure both Part A and Part B are extruded. Attach nozzle and dispense approximately 25 to 50mm before bonding. Partially used cartridges can be stored with the mixing nozzle attached. To reuse the cartridges, remove and discard the old nozzle, attach a new nozzle and dispense approximately 25 to 50mm before bonding.
4. Bulk containers: normal material is dispensed through volumetric meter mixing equipment and attached to static mix nozzles.
5. Application on the substrates should be made as soon as possible. Large volume of adhesives or high temperatures will accelerate the curing speed.
6. Join the adhesive coated surfaces with certain pressure. Higher temperatures will speed up the curing.
7. Keep the assembled parts from moving during curing. Prevent any service load before developing full bonding strength.
8. Uncured adhesive can be cleaned using ethyl alcohol.

Storage

Maximum shelf life may be obtained when product is stored in a cool, dry location at a temperature between **10°C to 28°C**.

TO PREVENT CONTAMINATION OF UNUSED PRODUCT, DO NOT RETURN ANY PRODUCT TO ITS ORIGINAL CONTAINER.

Materials Handling

Refer to the Material Safety Data Sheet (MSDS) for this product.

Disclaimer

The information provided here including the recommendations for use and application of the product is based on internal laboratory test conditions and should only be used as a reference. CollTech does not assume responsibility for the test or performance results obtained by the user. It is the responsibility of the user to perform their own evaluations to confirm whether this product is suitable for their application.

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